IN THE CLAIMS

1. (Previously Presented) A magnetoresistance-effect element comprising:
a magnetism-sensing section the electric resistance of which changes in
accordance with an external magnetic field;

a low-resistance metal layer contacting the magnetism-sensing section; and an oxide layer provided on that surface of the low-resistance metal layer which faces away from the magnetism-sensing section, wherein a total thickness of the low-resistance metal layer and oxide layer ranges from 0.5 nm to 1.5 nm.

- 2. (Original) The magnetoresistance-effect element according to claim 1, wherein the low-resistance metal layer is made of copper.
- 3. (Original) The magnetoresistance-effect element according to claim 1, wherein the oxide layer contains material that oxidizes the element constituting the low-resistance metal layer.
- 4. (Original) The magnetoresistance-effect element according to claim 1, wherein the magnetism-sensing section, a pinned layer the direction of magnetization of which is fixed by an anti-ferromagnetic layer, and a nonmagnetic metal layer interposed between the magnetism-sensing section and the pinned layer constitute a spin-valve film.
- 5. (Original) The magnetoresistance-effect element according to claim 4, wherein at least the anti-ferromagnetic layer, the pinned layer, the nonmagnetic metal layer, the magnetism-sensing section, the low-resistance metal layer and the oxide layer are provided on a substrate, laid one upon another in the order mentioned.
- 6. (Original) The magnetoresistance-effect element according to claim 5, wherein a protective layer is formed on the oxide layer.

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- 7. (Original) The magnetoresistance-effect element according to claim 4, wherein at least the oxide layer, the low-resistance metal layer, the magnetism-sensing section, the nonmagnetic metal layer, the pinned layer and the anti-ferromagnetic layer are provided on a substrate, one laid upon another in the order mentioned.
- 8. (Previously Presented) The magnetoresistance-effect element according to claim 1, wherein the magnetism-sensing section and a nonmagnetic metal layer are alternately laid, forming an artificial lattice film, and the low-resistance metal layer contacts the outermost magnetism-sensing section.
 - 9. (Cancelled)
- 10. (Previously Presented) A magnetoresistance-effect magnetic head comprising:
 - a substrate;
 - a pair of magnetic shield members provided on the substrate;
- a magnetoresistance-effect element interposed between the magnetic shield members;
- a pair of bias layers provided at the ends of longitudinal direction of the magnetoresistance-effect element; and
- a pair of lead electrodes provided in the form of thin film and arranged right above the bias layers,

wherein the magnetoresistance-effect element comprises a magnetism-sensing section the electric resistance of which changes in accordance with an external magnetic field, a low-resistance metal layer contacting the magnetism-sensing section, and an oxide layer provided on that surface of the low-resistance metal layer which faces away from the magnetism-sensing section, wherein a total thickness of the low-resistance metal layer and oxide layer ranges from 0.5 nm to 1.5 nm.

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- 11. (Original) The magnetoresistance-effect magnetic head according to claim 10, wherein the low-resistance metal layer is made of copper.
- 12. (Original) The magnetoresistance-effect magnetic head according to claim 10, wherein the oxide layer contains material that oxidizes the element constituting the low-resistance metal layer.
- 13. (Original) The magnetoresistance-effect magnetic head according to claim 10, wherein the magnetism-sensing section, a pinned layer the direction of magnetization of which is fixed by an anti-ferromagnetic layer, and a nonmagnetic metal layer interposed between the magnetism-sensing section and the pinned layer constitute a spin-valve film.
- 14. (Original) The magnetoresistance-effect magnetic head according to claim 13, wherein at least the anti-ferromagnetic layer, the pinned layer, the nonmagnetic metal layer, the magnetism-sensing section, the low-resistance metal layer and the oxide layer are provided on a substrate, laid one upon another in the order mentioned.
- 15. (Original) The magnetoresistance-effect magnetic head according to claim 14, wherein a protective layer is formed on the oxide layer.
- 16. (Original) The magnetoresistance-effect magnetic head according to claim 13, wherein at least the oxide layer, the low-resistance metal layer, the magnetism-sensing section, the nonmagnetic metal layer, the pinned layer and the anti-ferromagnetic layer are provided on a substrate, one laid upon another in the order mentioned.
- 17. (Original) The magnetoresistance-effect magnetic head according to claim 10, wherein magnetism-sensing sections and nonmagnetic metal layers are alternately laid, forming an artificial lattice film, and the low-resistance metal layer contacts the outermost magnetism-sensing section.

18. (Cancelled)

19. (Withdrawn) A method of manufacturing a magnetoresistance-effect element having a magnetism-sensing section the electric resistance of which changes in accordance with an external magnetic field, said method comprising:

a first step of forming the magnetism-sensing section and a low-resistance metal layer on a substrate, in the order mentioned; and

a second step of forming an oxide layer by oxidizing that surface of the low-resistance metal layer which faces away from the magnetism-sensing section.

- 20. (Withdrawn) The method according to claim 19, wherein a protective layer is formed on the low-resistance metal layer in the first step, and that surface of the low-resistance metal which faces away from the magnetism-sensing section is oxidized in the second step, by applying oxygen through the protective layer.
- 21. (Withdrawn) The method according to claim 20, wherein the protective layer has a thickness of 1 nm or less.
- 22. (Withdrawn) The method according to claim 20, wherein the protective layer contains tantalum.
- 23. (Withdrawn) The method according to claim 19, wherein at least an anti-ferromagnetic layer, a pinned layer whose direction of magnetization is fixed by the anti-ferromagnetic layer, a nonmagnetic layer, the magnetism-sensing section and a low-resistance metal layer are formed in the first step on the substrate in the order mentioned.
- 24. (Withdrawn) The method according to claim 19, wherein at least an artificial lattice layer composed of the magnetism-sensing sections and nonmagnetic layers alternately

laid, one on another, and the low-resistance metal layer are formed in the first step on the substrate in the order mentioned.

25. (Withdrawn) A method of manufacturing a magnetoresistance-effect element having a magnetism-sensing section the electric resistance of which changes in accordance with an external magnetic field, said method comprising:

a first step of forming a low-resistance metal layer and the magnetism-sensing section on a substrate, in the order mentioned; and

a second step of forming an oxide layer by oxidizing that surface of the low-resistance metal layer which faces away from the magnetism-sensing section.

- 26. (Withdrawn) The method according to claim 25, wherein a primary-coat layer made of oxide is formed in the first step, on that surface of the low-resistance metal layer which faces away from the magnetism-sensing section.
- 27. (Withdrawn) The method according to claim 25, wherein at least the low-resistance metal layer, the magnetism-sensing section, a nonmagnetic layer, a pinned layer whose direction of magnetization is fixed by an anti-ferromagnetic layer, and the anti-ferromagnetic layer are formed in the first step on the substrate in the order mentioned.
- 28. (Withdrawn) The method according to claim 25, wherein at least the low-resistance metal layer, and an artificial lattice layer composed of the magnetism-sensing sections and nonmagnetic layers alternately laid, one on another, are formed in the first step on the substrate in the order mentioned.